



FOR IMMEDIATE RELEASE

Aehr Test Systems

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**Aehr Test Systems Receives Follow-on Order for
FOX-XP™ Test and Burn-in System for Silicon Photonics Devices**

Fremont, CA (December 14, 2017) – Aehr Test Systems (NASDAQ: AEHR), a worldwide supplier of semiconductor test and burn-in equipment, today announced that it has received a follow-on order from one of its lead FOX-XP Test and Burn-in System customers to provide additional test capacity to meet the customer’s increasing silicon photonics device production requirements. The FOX-XP system order includes down payments per Aehr Test’s standard terms and conditions of sale. The system is expected to ship in the first half of calendar 2018.

Gayn Erickson, President and CEO of Aehr Test Systems, commented, “We continue to work closely with this lead customer to enhance our FOX-XP solutions to increase and upgrade their test capabilities and capacity. They were our first customer for a full production FOX-XP system, and they followed with an order to upgrade that initial test cell to not only improve the testing capability for this application by increasing the voltage capability of each of the tester channels, but also to increase the power handling capability of their configuration from 1,000 watts to 2,000 watts per wafer.

“We are excited to receive this follow-on order for an additional full wafer test and burn-in system that includes 100 percent coverage of all die on the wafer and diagnostic capability to ensure 100 percent validation of the burn-in test. We believe that doing full wafer test and burn-in with the FOX-XP system significantly lowers the overall cost of test for the customer due to the FOX-XP system’s ability to prove device quality and remove infant mortality before the device is installed in the end use product.

“The unique ability of the FOX-XP system and its proprietary WaferPak and DiePak contactors to weed out infant mortality defects in optical transceivers and sensors has made it ideally suited for mass production testing of devices such as silicon photonics, VCSELs (vertical cavity surface-emitting lasers) and LEDs in wafer, singulated die and module forms. We believe this is the front end of a wave of opportunity for Aehr Test created by the need for semiconductors, modules, and systems that must operate over long periods of time for applications where security, safety, and customer and consumer confidence are absolutely critical.”

The FOX-XP system, available in multi-wafer and singulated die/module test configurations, is capable of functional test and burn-in/cycling of VCSELs, integrated optical devices, 2D and 3D sensors, magnetic sensors, flash memories, microcontrollers, and other leading-edge ICs in either wafer form, before they are assembled into single or multi-die stacked packages, or in singulated die/module form. A single FOX-XP test system may be configured with up to 18 blades of wafer test resources, enabling up to 18 wafers to be tested simultaneously handling 1 kW or nine wafers at up to 2 kW per wafer. Each slot may be configured with up to eight Universal Channel Channel Modules (UCCMs), High Current Channel Modules (HCCMs), or High Voltage Channel Modules (HVCMs) to

supply device stimulus to test/burn-in/cycle die or modules. The footprint of the 18-wafer test system is similar to the footprint of typical semiconductor Automatic Test Equipment (ATE) that can only test one wafer at a time.

The FOX-XP system utilizes Aehr Test's FOX WaferPak™ contactor, which provides a cost-effective solution for making full wafer electrical die contact in a multi-wafer environment. Aehr Test's WaferPak contactors contain up to tens of thousands of probes to contact all die simultaneously on wafers and substrates up to 300mm. Another key component of the FOX-XP system is the FOX WaferPak Aligner, which provides fully automatic alignment of the customer's wafers to the WaferPak contactor.

About Aehr Test Systems

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic, optical and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, incremental capacity needs, and new opportunities for Aehr Test products in package, wafer level, and singulated die/module level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX-P™ families of test and burn-in systems and FOX WaferPak Aligner, FOX-XP WaferPak Contactor, and FOX DiePak® Carrier. The ABTS system is used in production and qualification testing of packaged parts for lower power and higher power logic devices as well as all common types of memory devices. The FOX-XP system is a full wafer contact and singulated die/module test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers, systems-on-a-chip, and integrated optical devices. The WaferPak contactor contains a unique full wafer probe card capable of testing wafers up to 300mm that enables IC manufacturers to perform test and burn-in of full wafers on Aehr Test FOX systems. The DiePak Carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of both bare die and modules. For more information, please visit Aehr Test System's website at www.aehr.com.

Safe Harbor Statement

This press release contains certain forward-looking statements based on current expectations, forecasts and assumptions that involve risks and uncertainties. These statements are based on information available to Aehr Test as of the date hereof and actual results could differ materially from those stated or implied due to risks and uncertainties. Forward-looking statements include statements regarding Aehr Test's expectations, beliefs, intentions or strategies regarding the FOX products, including statements regarding future market opportunities and conditions, expected product shipment dates and customer orders or commitments. These risks and uncertainties include, without limitation, acceptance by customers of the FOX and WaferPak Contactor technologies, acceptance by customers of the FOX-XP system, WaferPak Aligners, DiePak Loader/Unloaders, WaferPak Contactors and DiePak Carriers shipped upon receipt of a purchase order and the ability of new products to meet customer needs or perform as described, as well as general market conditions, customer demand and acceptance of Aehr Test's products and Aehr Test's ability to execute on its business strategy. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the Securities and Exchange Commission for a more detailed description of the risks facing Aehr Test's business. Aehr Test disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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